

**AMENDMENTS TO THE CLAIMS**

1-10. (Cancelled)

11. (New) An electronic device testing apparatus, for conducting a test of electronic devices prior to molded at least by pressing input/output terminals of said electronic devices against a contact portions of a test head while said electronic devices are loaded on a strip format, comprising:

one or a plurality of moving means capable of gripping a plurality of said strip formats, conveying said strip formats to said contact portions without reloading said electronic devices from said strip formats, and pressing input/output terminals of said electronic devices against said contact portions at a time while said electronic devices are loaded on said strip formats.

12. (New) The electronic device testing apparatus as set forth in claim 11, wherein said moving means is capable of freely selecting the gripping number within the number able to be gripped.

13. (New) The electronic device testing apparatus as set forth in claim 11, wherein said one moving means is capable of freely selecting the gripping number being independent from other moving means.

14. (New) The electronic device testing apparatus as set forth in claim 11, wherein said any two or more moving means among said plurality of moving means have a substantially overlapping operation range on a contact group as a set of said contact portions.

15. (New) The electronic device testing apparatus as set forth in claim 11, wherein each of said moving means grips and moves said strip format from a loading position of pre-test electronic devices to said contact portions.

16. (New) The electronic device testing apparatus as set forth in claim 11, wherein each of said moving means grips and moves said strip format from said contact portions to a loading position of post-test electronic devices.

17. (New) The electronic device testing apparatus as set forth in claim 11, wherein a sum of the numbers of contact portions in said test head is  $2^n$  ("n" is a natural number).

18. (New) The electronic device testing apparatus as set forth in claim 17, wherein n=5 or n=6.

19. (New) An electronic device testing apparatus, for conducting a test of electronic devices by pressing input/output terminals of said electronic devices against contact portions of a test head while said electronic devices are formed on a wafer, comprising:

one or a plurality of moving means capable of gripping a plurality of said wafers, conveying said wafers to said contact portions, and pressing input/output terminals of said electronic devices against said contact portions at a time while said electronic devices are formed on said wafers.

20. (New) The electronic device testing apparatus as set forth in claim 19, wherein said moving means is capable of freely selecting the gripping number within the number able to be gripped.

21. (New) The electronic device testing apparatus as set forth in claim 19, wherein said one moving means is capable of freely selecting the gripping number being independent from other moving means.

22. (New) The electronic device testing apparatus as set forth in claim 19, wherein said any two or more moving means among said plurality of moving means have a substantially overlapping operation range on a contact group as a set of said contact portions.

23. (New) The electronic device testing apparatus as set forth in claim 19, wherein each of said moving means grips and moves said wafer from a loading position of pre-test electronic devices to said contact portions.

24. (New) The electronic device testing apparatus as set forth in claim 19, wherein each of said moving means grips and moves said wafer from said contact portions to a loading position of post-test electronic devices.

25. (New) The electronic device testing apparatus as set forth in claim 19, wherein a sum of the numbers of contact portions in said test head is  $2^n$  ("n" is a natural number).

26. (New) The electronic device testing apparatus as set forth in claim 25, wherein n=5 or n=6.